



Product Change Notification

108723 - 02

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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Product Change Notification

Change Notification #: 108723 - 02
Change Title: S5000XAL, PCN 108723-02, Product Design, Fab Spin to Improve CPU FSB Routing, Reason for Revision: Date Customer Must be Ready to Receive Post-Conversion Material is postponed.
Date of Publication: November 13, 2008

Key Characteristics of the Change:

Product Design

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material:	Nov 24, 2008
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Description of Change to the Customer:

Reason for Revision: Date Customer Must be Ready to Receive Post-Conversion Material is postponed.

Intel is implementing a printed circuit board (PCB) change to improve the Front Side Bus (FSB) routing for the secondary processor. This design change will result in better signal quality. Replace existing processor VR heatsink with anodized heatsink.

Customer Impact of Change and Recommended Action:

No customer impact is being projected. However, standard board validation testing is highly recommended.

Products Affected / Intel Ordering Codes:

Pre Change Product Code	Pre Change MM#	Pre Change TA	Pre Change PBA	Post Change Product Code	Post Change MM#	Post Change TA	Post Change PBA
BB5000XALR	897196	E11682-903	D46952-903	BB5000XALR	900396	E51577-100	E50387-100

Reference Documents / Attachments:

Document: _____ **Location #:** _____

PCN Revision History:

Date of Revision:

August 20, 2008

November 4, 2008

November 13, 2008

Revision Number:

00

01

02

Reason:

Originally Published PCN

Add PBA number

Date Customer Must be Ready to
Receive Post-Conversion Material
is postponed.